



PTC thermistors for overcurrent protection in telecom applications

Telecom Pair Protector (TPP), SMD

Series/Type:

Date: November 2012

Overcurrent protection for telecom

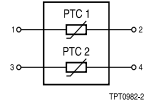
Telecom pair protector (TPP), SMD

SMD

Applications

- Overcurrent protection for telecom applications
- Suitable for line card applications e.g. POTS, access networks, customer premises equipment (CPE) or integrated voice data (IVD)

Internal circuit



Features

- Two resistance-matched PTCs in a plastic housing
- Compliant with ITU-T standards
 - basic-level lightning surges (10/700 μ s)
 - basic-level power induction (600 V, 1 A, 0.2 s)
 - power contact criteria A/B (230 V, 15 min.)
- Compliant with GR-1089 AC power contact 120 V, 25 A, 15 min.
- Suitable for continuous connection to mains voltages of 110/230 V AC in tripped (high-ohmic) condition
- Housing material to UL94-V0
- UL approval to UL 1434 (file number E69802) for selected types
- Tight resistance matching maintained after switching
- Negligible resistance drift after reflow soldering or switching
- Marked with manufacturer's logo, type designation and date code
- RoHS-compatible

Options

- Alternative tolerances and resistances on request


Delivery mode

- T15**: Blister tape, 330-mm reel with 16-mm tape, taping to IEC 60286-3
- T17** and T18**: Blister tape, 380-mm reel with 24-mm tape, taping to IEC 60286-3

General technical data

Maximum fault voltage		$V_{F,max}$	245	V AC
Max. operating voltage		V_{max}	135	V AC
Operating temperature range	(V = 0)	T_{op}	20/+125	°C
Operating temperature range	(V = V_{max})	T_{op}	0/+60	°C
Insulating test voltage between PTC1 and PTC2		V_{ins}	> 3	kV
Resistance matching in one housing	for R_R £ 4.75 W	R_2 R_1	< 0.5	W
Resistance matching in one housing	for R_R £ 50 W	R_2 R_1	< 1.0	W
Resistance matching in one housing	for R_R = 75 W	R_2 R_1	< 2.0	W

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Electrical specifications and ordering codes

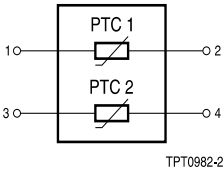
Type	R _R W	DR _R %	I _R @ 25 °C mA	I _R @ 70 °C mA	I _S @ 25 °C mA	I _{Smax} A	Approvals 	Ordering code
Component height 7.5								
T1535	35	+15/ 20	110	70	230	2.5		B59535T1120A262
T1550	50	±15	90	60	190	2.5		B59550T1120A262
Component height 8.5								
T1509	9	±10	180	120	360	1.0		B59509T1120A062
T1510	10	±20	180	120	360	1.0		B59510T1120A062
T1525	25	±20	130	85	260	2.8		B59525T1120A062
Component height 10.5								
T1725	25	±20	130	85	260	2.8		B59725T1120A062
T1735	35	+15/ 20	110	70	230	4.6	X	B59735T1120A062
T1750	50	±15	90	60	190	2.5	X	B59750T1120A062
Component height 11.5								
T1805	4.75	+15/ 20	160	70	370	1.0	X	B59805T1080A062
T1810	10	±20	180	120	360	1.0		B59810T1120A062
T1825	25	±20	130	85	260	2.8		B59825T1120A062
T1835	35	+15/ 20	110	70	230	4.6	X	B59835T1120A062
T1850	50	±15	90	60	190	2.5	X	B59850T1120A062
T1875	75	±20	70	40	150	2.5	X	B59875T1120A062

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Switching times and ordering codes

Type	t_s (typ.) @ I_{Smax} s	t_s (typ.) @ 1 A s	t_s (typ.) @ 500 mA s	Ordering code
Component height 7.5				
T1535	0.07	0.4	1.6	B59535T1120A262
T1550	0.05	0.3	1.1	B59550T1120A262
Component height 8.5				
T1509	4	4	20	B59509T1120A062
T1510	3.6	3.6	16	B59510T1120A062
T1525	0.2	1.4	6	B59525T1120A062
Component height 10.5				
T1725	0.3	1.1	4	B59725T1120A062
T1735	0.04	0.8	3.4	B59735T1120A062
T1750	0.1	0.6	2.4	B59750T1120A062
Component height 11.5				
T1805	4	4	20	B59805T1080A062
T1810	3.8	3.8	19.0	B59810T1120A062
T1825	0.2	1.5	6.5	B59825T1120A062
T1835	0.06	1.1	4.5	B59835T1120A062
T1850	0.13	0.8	3.1	B59850T1120A062
T1875	0.12	0.7	2.6	B59875T1120A062

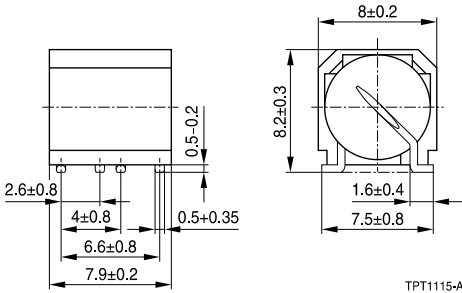
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Internal circuit

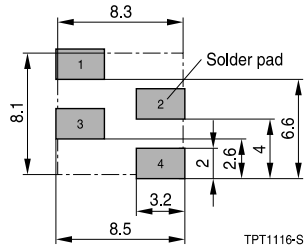


Dimensional drawings in mm

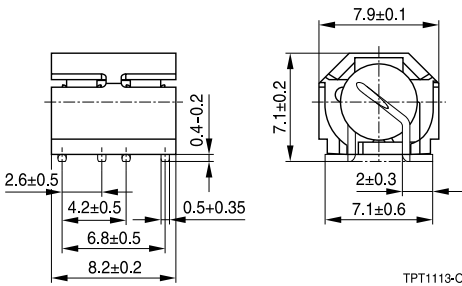
For type T1509, T1510 and T1525



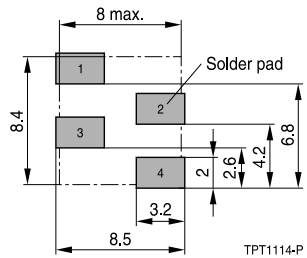
Solder pad



For type T1535 and T1550



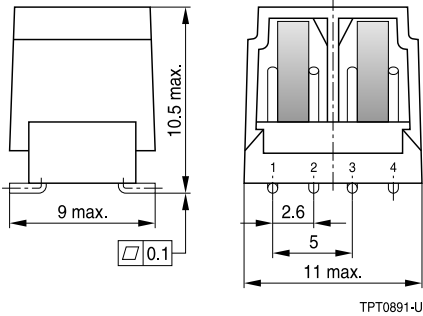
Solder pad



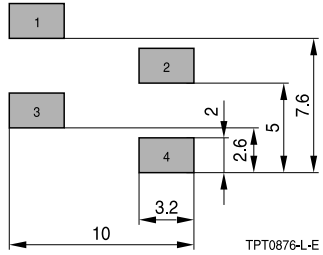
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Dimensional drawings in mm

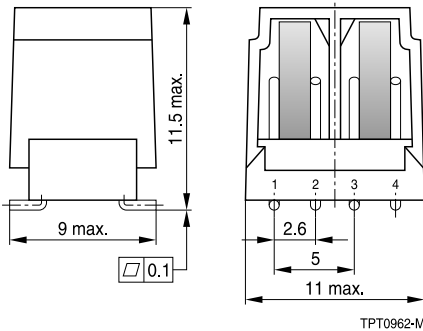
For type T1725, T1735, T1750



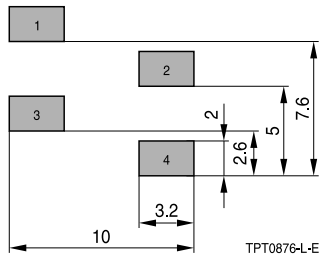
Solder pad



For type T1805 ... T1875



Solder pad



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Reliability data

Test	Standard	Test conditions	DR_{25}/R_{25}
Electrical endurance, cycling	IEC 60738-1	Room temperature, I_{Smax}, V_{max} Number of cycles: 10	< 20%
Electrical endurance, constant	IEC 60738-1	Storage at $V_{max}/T_{op,max}$ (V_{max}) Test duration: 1000 h	< 25%
Damp heat	IEC 60738-1	Temperature of air: 40 °C Relative humidity of air: 93% Duration: 56 days Test according to IEC 60068-2-78	< 10%
Rapid change of temperature	IEC 60738-1	$T_1 = T_{op,min}$ (0 V), $T_2 = T_{op,max}$ (0 V) Number of cycles: 5 Test duration: 30 min Test according to IEC 60068-2-14, test Na	< 10%
Vibration	IEC 60738-1	Frequency range: 10 to 55 Hz Displacement amplitude: 0.75 mm Test duration: 3 ´ 2 h Test according to IEC 60068-2-6, test Fc	< 5%
Shock	IEC 60738-1	Acceleration: 390 m/s ² Pulse duration: 6 ms; 6 ´ 4000 pulses	< 5%
Climatic sequence	IEC 60738-1	Dry heat: $T = T_{op,max}$ (0 V) Test duration: 16 h Damp heat first cycle Cold: $T = T_{op,min}$ (0 V) Test duration: 2 h Damp heat 5 cycles Tests performed according to IEC 60068-2-30	< 10%

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ITU performance overview and fault conditions

	Test no.	ITU K20		ITU K21		ITU K45	
		Basic test level	Enhanced test level	Basic test level	Enhanced test level	Basic test level	Enhanced test level
Power induction	1	A	A	A	A	A	A
	2	B	C	B	C	B	C
Power contact	3	D	E	D	E	D	E
Lightning surge	4	F	G	G	G	G	G
	5	H	H	H	I	H	H

Power induction	A	600 V AC, R = 600 W, t = 0.2 s, criteria A
	B	600 V AC, R = 600 W, t = 1.0 s, with GDT, criteria A
	C	1500 V AC, R = 200 W, t = 2.0 s, with GDT, criteria A
Power contact	D	230 V AC, t = 15 min, R = 10 ... 1000 W, criteria B
	E	230 V AC, t = 15 min, R = 10, 20, 40, 80, 1000 W, criteria B, R = 160, 300, 600 W, criteria A
Lightning surge	F	$V_{c(max)} = 1.0$ kV, R = 25 W, t = 10/700 μ s, without GDT, criteria A
	G	$V_{c(max)} = 1.5$ kV, R = 25 W, t = 10/700 μ s, without GDT, criteria A
	H	$V_{c(max)} = 4.0$ kV, R = 25 W, t = 10/700 μ s, with GDT, criteria A
	I	$V_{c(max)} = 6.0$ kV, R = 25 W, t = 10/700 μ s, with GDT, criteria A

Criteria A: no damage, function must be fulfilled.

Criteria B: no fire hazard.

Electrical requirements according to GR-1089 standard for AC power contact

AC voltage: 120 V, 50 Hz, short circuit current 25 A, time 15 min, criteria A.

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Cautions and warnings

General

- EPCOS thermistors are designed for specific applications and should not be used for purposes not identified in our specifications, application notes and data books unless otherwise agreed with EPCOS during the design-in-phase.
- Ensure suitability of thermistor through reliability testing during the design-in phase. The thermistors should be evaluated taking into consideration worst-case conditions.

Storage

- Store thermistors only in original packaging. Do not open the package before storage.
- Storage conditions in original packaging: storage temperature 25 °C ... +45 °C, relative humidity £75% annual mean, maximum 95%, dew precipitation is inadmissible.
- Avoid contamination of thermistors surface during storage, handling and processing.
- Avoid storage of thermistor in harmful environment with effect on function on long-term operation (examples given under operation precautions).
- Use thermistor within the following period after delivery:

Through-hole devices (housed and leaded PTCs): 24 months

Motor protection sensors, glass-encapsulated sensors and probe assemblies: 24 months

Telecom pair and quattro protectors (TPP, TQP): 24 months

Leadless PTC thermistors for pressure contacting: 12 months

Leadless PTC thermistors for soldering: 6 months

SMDs in EIA sizes 3225 and 4032, and for PTCs with metal tags: 24 months

SMDs in EIA sizes 0402, 0603, 0805 and 1210: 12 months

Handling

- PTCs must not be dropped. Chip-offs must not be caused during handling of PTCs.
- Components must not be touched with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.

Soldering (where applicable)

- Use rosin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.
- Standard PTC heaters are not suitable for soldering.

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Mounting

- Electrode must not be scratched before/during/after the mounting process.
- Contacts and housing used for assembly with thermistor have to be clean before mounting. Especially grease or oil must be removed.
- When PTC thermistors are encapsulated with sealing material, the precautions given in chapter "Mounting instructions", "Sealing and potting" must be observed.
- When the thermistor is mounted, there must not be any foreign body between the electrode of the thermistor and the clamping contact.
- The minimum force of the clamping contacts pressing against the PTC must be 10 N.
- During operation, the thermistor's surface temperature can be very high. Ensure that adjacent components are placed at a sufficient distance from the thermistor to allow for proper cooling at the thermistors.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of thermistor. Be sure that surrounding parts and materials can withstand this temperature.
- Avoid contamination of thermistor surface during processing.

Operation

- Use thermistors only within the specified temperature operating range.
- Use thermistors only within the specified voltage and current ranges.
- Environmental conditions must not harm the thermistors. Use thermistors only in normal atmospheric conditions. Avoid use in deoxidizing gases (chlorine gas, hydrogen sulfide gas, ammonia gas, sulfuric acid gas etc), corrosive agents, humid or salty conditions. Contact with any liquids and solvents should be prevented.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by abnormal function (e.g. use VDR for limitation of overvoltage condition).

This listing does not claim to be complete, but merely reflects the experience of EPCOS AG.

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Symbols and terms

A	Area
C	Capacitance
C_{th}	Heat capacity
f	Frequency
I	Current
I_{max}	Maximum current
I_R	Rated current
I_{res}	Residual current
I_{PTC}	PTC current
I_r	Residual current
$I_{r,oil}$	Residual current in oil (for level sensors)
$I_{r,air}$	Residual current in air (for level sensors)
I_{RMS}	Root-mean-square value of current
I_S	Switching current
I_{Smax}	Maximum switching current
LCT	Lower category temperature
N	Number (integer)
N_c	Operating cycles at V_{max} , charging of capacitor
N_f	Switching cycles at V_{max} , failure mode
P	Power
P_{25}	Maximum power at 25 °C
P_{el}	Electrical power
P_{diss}	Dissipation power
R_G	Generator internal resistance
R_{min}	Minimum resistance
R_R	Rated resistance
DR_R	Tolerance of R_R
R_P	Parallel resistance
R_{PTC}	PTC resistance
R_{ref}	Reference resistance
R_S	Series resistance
R_{25}	Resistance at 25 °C
$R_{25,match}$	Resistance matching per reel/ packing unit at 25 °C
DR_{25}	Tolerance of R_{25}
T	Temperature
t	Time
T_A	Ambient temperature
t_a	Thermal threshold time

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T_C	Ferroelectric Curie temperature
t_E	Settling time (for level sensors)
T_R	Rated temperature
T_{sense}	Sensing temperature
T_{op}	Operating temperature
T_{PTC}	PTC temperature
t_R	Response time
T_{ref}	Reference temperature
T_{Rmin}	Temperature at minimum resistance
t_S	Switching time
T_{surf}	Surface temperature
UCT	Upper category temperature
V or V_{el}	Voltage (with subscript only for distinction from volume)
$V_{c(max)}$	Maximum DC charge voltage of the surge generator
$V_{F,max}$	Maximum voltage applied at fault conditions in protection mode
V_{RMS}	Root-mean-square value of voltage
V_{BD}	Breakdown voltage
V_{ins}	Insulation test voltage
$V_{link,max}$	Maximum link voltage
V_{max}	Maximum operating voltage
$V_{max,dyn}$	Maximum dynamic (short-time) operating voltage
V_{meas}	Measuring voltage
$V_{meas,max}$	Maximum measuring voltage
V_R	Rated voltage
V_{PTC}	Voltage drop across a PTC thermistor
α	Temperature coefficient
D	Tolerance, change
d_{th}	Dissipation factor
t_{th}	Thermal cooling time constant
λ	Failure rate
e	Lead spacing (in mm)

Abbreviations / Notes

SMD Surface-mount devices

* To be replaced by a number in ordering codes, type designations etc.

+ To be replaced by a letter

All dimensions are given in mm.

The commas used in numerical values denote decimal points.

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